Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1609-01** DATE: **14-Sep-2016**

Product Affected: 4DB0226KB0AVG(8)
(built in FCCSP-53)

Date Effective: **14-Dec-2016**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
- ☒ Back Mark
- ☐ Date Code
- ☐ Other

Lot # will have:
"RC" prefix for ASECL, Taiwan

Contact: IDT PCN DESK

E-mail: pcndesk@idt.com

Attachment: ☒ Yes ☐ No

Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☒ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at ASEK, Taiwan; SFA, Korea and Stats ChipPac, Korea.

There is no change to the moisture performance.

Attachment I details the qualification results.

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ______________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ______________________

E-Mail Address: ______________________

Title: ______________________

Phone# /Fax# : ______________________

CUSTOMER COMMENTS: ______________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ______________________

DATE: ______________________

ATTACHMENT I - PCN # : A1609-01

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at ASEK, Taiwan; SFA, Korea and Stats ChipPac, Korea.

The material set details of the current and alternate assembly location is as shown in Table 1. The material set used at the alternate site, ASECL is the same as ASEK.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (ASE Kaohsiung, Taiwan & SFA, Korea & Stats ChipPac, Korea)	**Alternate Assembly (ASE Chungli, Taiwan)**
Die Bump	40Cu/3Ni/27SnAg	40Cu/3Ni/27SnAg
Mold Compound	EME-G311A Type C/ Panasonic CV8710U/ KEG-1250FC-K	EME-G311A Type C
Substrate	ABF-GX13/E700GR core	ABF-GX13/E700GR core
Solder Balls	LF35	LF35

ATTACHMENT I - PCN # : A1609-01

Qualification Information and Qualification Data:

Affected Packages: FCCSP-53

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: FCCSP-53

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test